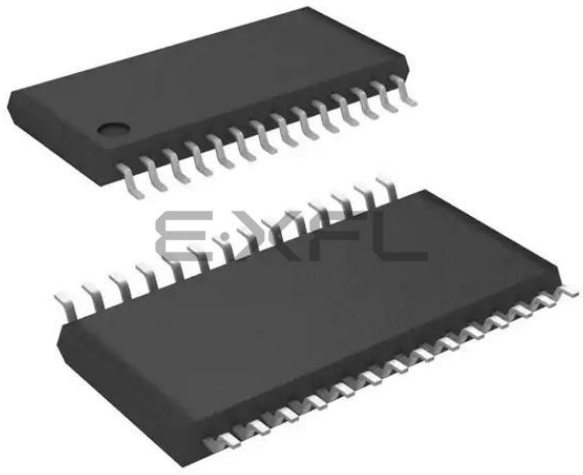

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI, SPI
Peripherals	LVD, POR, PWM
Number of I/O	24
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	28-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc908qc16cdre

Chapter 9
Low-Voltage Inhibit (LVI)

Chapter 10
Oscillator Mode (OSC)

Features of the CPU08 include the following:

- Enhanced HC05 programming model
- Extensive loop control functions
- 16 addressing modes (eight more than the HC05)
- 16-bit index register and stack pointer
- Memory-to-memory data transfers
- Fast 8 × 8 multiply instruction
- Fast 16/8 divide instruction
- Binary-coded decimal (BCD) instructions
- Optimization for controller applications
- Efficient C language support

1.3 MCU Block Diagram

Figure 1-1 shows the structure of the MC68HC908QC16, MC68HC908QC8, and MC68HC908QC4.

1.4 Pin Assignments

The MC68HC908QC16, MC68HC908QC8, and MC68HC908QC4 are available in 16-pin, 20-pin, and 28-pin packages. Figure 1-2 shows the pin assignment for these packages.

1.5 Pin Functions

Table 1-2 provides a description of the pin functions.

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
$0242	TIM2 Counter Register Low (T2CNTL) See page 214.	Read:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
$0243	TIM2 Counter Modulo Register High (T2MODH) See page 215.	Read:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
		Write:								
		Reset:	1	1	1	1	1	1	1	1
$0244	TIM2 Counter Modulo Register Low (T2MODL) See page 215.	Read:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Write:								
		Reset:	1	1	1	1	1	1	1	1
$0245	TIM2 Channel 0 Status and Control Register (T2SC0) See page 215.	Read:	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	TOV0	CH0MAX
		Write:	0							
		Reset:	0	0	0	0	0	0	0	0
$0246	TIM2 Channel 0 Register High (T2CH0H) See page 218.	Read:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
		Write:								
		Reset:	Indeterminate after reset							
$0247	TIM2 Channel 0 Register Low (T2CH0L) See page 218.	Read:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Write:								
		Reset:	Indeterminate after reset							
$0248	TIM2 Channel 1 Status and Control Register (T2SC1) See page 215.	Read:	CH1F	CH1IE	0	MS1A	ELS1B	ELS1A	TOV1	CH1MAX
		Write:	0							
		Reset:	0	0	0	0	0	0	0	0
$0249	TIM2 Channel 1 Register High (T2CH1H) See page 218.	Read:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
		Write:								
		Reset:	Indeterminate after reset							
$024A	TIM2 Channel 1 Register Low (T2CH1L) See page 218.	Read:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Write:								
		Reset:	Indeterminate after reset							
$024B	Reserved									
$024C	Periodic Wakeup Status and Control Register (PWUSC) See page 119.	Read:	0	0	PWUON	PWUCLK-SEL	PWUF	0	PWUIE	SMODE
		Write:						PWUACK		
		Reset:	0	0	0	0	0	0	0	0
$024D	Periodic Wakeup Prescaler Register (PWUP) See page 120.	Read:	0	0	0	0	PS3	PS2	PS1	PS0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
$024E	Periodic Wakeup Modulo Register (PWUMOD) See page 121.	Read:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Write:								
		Reset:	0	0	0	0	0	0	0	0

= Unimplemented R = Reserved U = Unaffected

Figure 2-2. Control, Status, and Data Registers (Sheet 6 of 8)

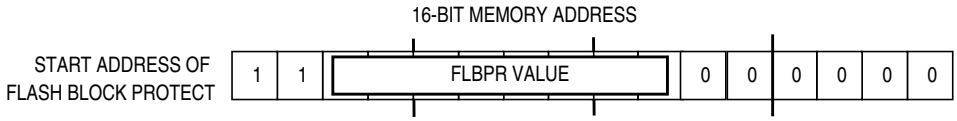


Figure 2-6. FLASH Block Protect Start Address

Table 2-2. Examples of Protect Start Address

BPR[7:0]	Start of Address of Protect Range(1)
$00(2)	The entire FLASH memory is protected.
$01 (**0000 0001**)	$C040 (11**00 0000 01**00 0000)
$02 (**0000 0010**)	$C080 (11**00 0000 10**00 0000)
$03 (**0000 0011**)	$C0C0 (11**00 0000 11**00 0000)
and so on...	
$FD (**1111 1101**)	$FF40 (11**11 1111 01**00 0000)
$FE (**1111 1110**)	$FF80 (11**11 1111 10**00 0000)
$FF	The entire FLASH memory is not protected.

1. The end address of the protected range is always $FFFF.
2. $BE00–$BFFF is always protected unless the entire FLASH memory is unprotected, BPR[7:0] = $FF.

2.6.7 EEPROM Memory Emulation Using FLASH Memory

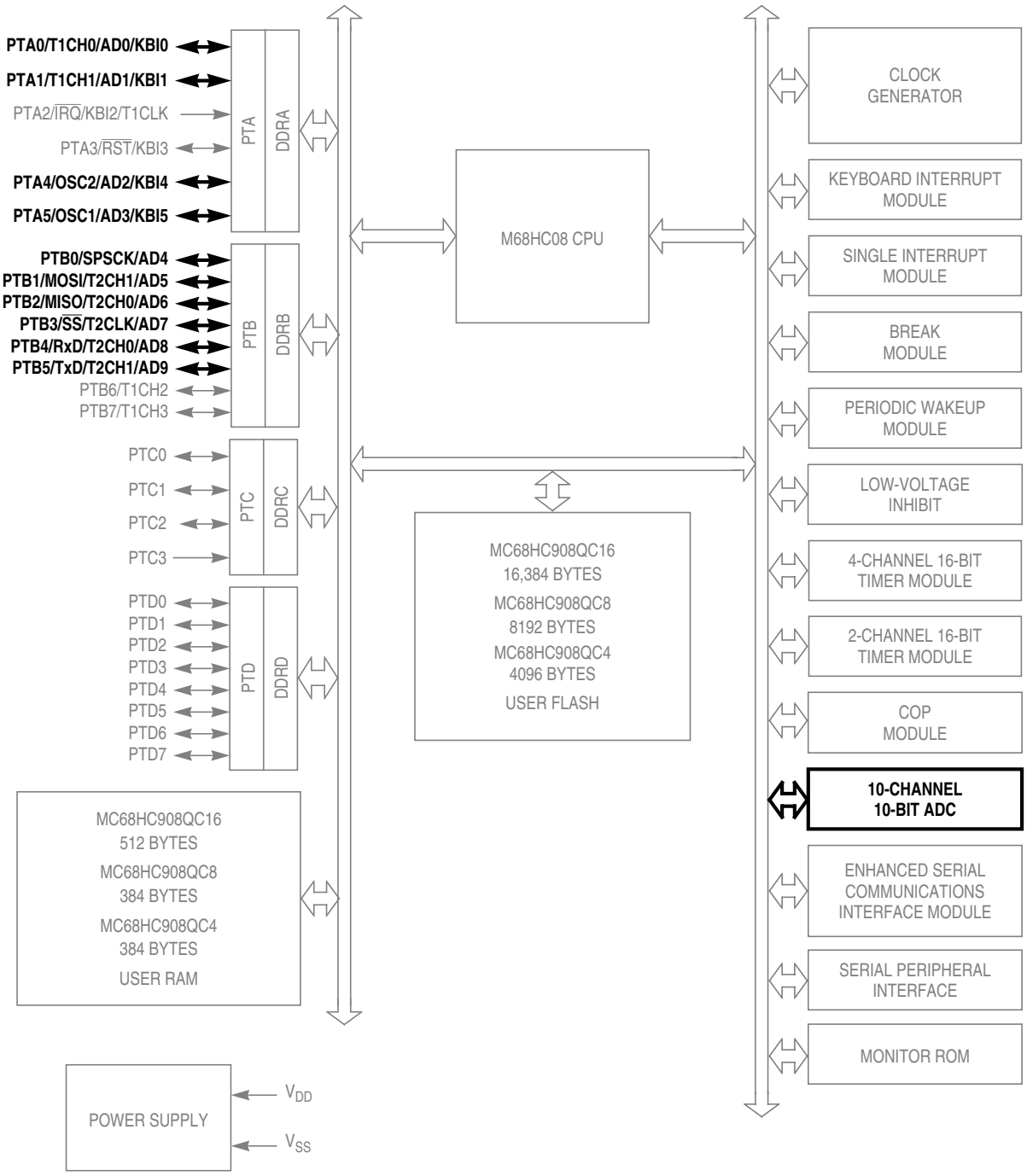
In some applications, the user may want to repeatedly store and read a set of data from an area of nonvolatile memory. This is easily implemented in EEPROM memory because single byte erase is allowed in EEPROM.

When using FLASH memory, the minimum erase size is a page. However, the FLASH can be used as EEPROM memory. This technique is called “EEPROM emulation”.

The basic concept of EEPROM emulation using FLASH is that a page is continuously programmed with a new data set without erasing the previously programmed locations. Once the whole page is completely programmed or the page does not have enough bytes to program a new data set, the user software automatically erases the page and then programs a new data set in the erased page.

In EEPROM emulation when data is read from the page, the user software must find the latest data set in the page since the previous data still remains in the same page. There are many ways to monitor the page erase timing and the latest data set. One example is unprogrammed FLASH bytes are detected by checking programmed bytes (non-$FF value) in a page. In this way, the end of the data set will contain unprogrammed data ($FF value).

A couple of application notes, describing how to emulate EEPROM using FLASH, are available on our web site. Titles and order numbers for these application notes are given at the end of this subsection.



All port pins can be configured with internal pullup
PTC not available on 16-pin devices (see note in 11.1 Introduction)
PTD not available on 16-pin or 20-pin devices (see note in 11.1 Introduction)

Figure 3-1. Block Diagram Highlighting ADC10 Block and Pins

3.3.4 Sources of Error

Several sources of error exist for ADC conversions. These are discussed in the following sections.

3.3.4.1 Sampling Error

For proper conversions, the input must be sampled long enough to achieve the proper accuracy. Given the maximum input resistance of approximately 15 kΩ and input capacitance of approximately 10 pF, sampling to within 1/4LSB (at 10-bit resolution) can be achieved within the minimum sample window (3.5 cycles / 2 MHz maximum ADCK frequency) provided the resistance of the external analog source (R_{AS}) is kept below 10 kΩ. Higher source resistances or higher-accuracy sampling is possible by setting ADLSMP (to increase the sample window to 23.5 cycles) or decreasing ADCK frequency to increase sample time.

3.3.4.2 Pin Leakage Error

Leakage on the I/O pins can cause conversion error if the external analog source resistance (R_{AS}) is high. If this error cannot be tolerated by the application, keep R_{AS} lower than V_{ADVIN} / (4096*I_{Leak}) for less than 1/4LSB leakage error (at 10-bit resolution).

3.3.4.3 Noise-Induced Errors

System noise which occurs during the sample or conversion process can affect the accuracy of the conversion. The ADC10 accuracy numbers are guaranteed as specified only if the following conditions are met:

- There is a 0.1µF low-ESR capacitor from V_{REFH} to V_{REFL} (if available).
- There is a 0.1µF low-ESR capacitor from V_{DDA} to V_{SSA} (if available).
- If inductive isolation is used from the primary supply, an additional 1µF capacitor is placed from V_{DDA} to V_{SSA} (if available).
- V_{SSA} and V_{REFL} (if available) is connected to V_{SS} at a quiet point in the ground plane.
- The MCU is placed in wait mode immediately after initiating the conversion (next instruction after write to ADSCR).
- There is no I/O switching, input or output, on the MCU during the conversion.

There are some situations where external system activity causes radiated or conducted noise emissions or excessive V_{DD} noise is coupled into the ADC10. In these cases, or when the MCU cannot be placed in wait or I/O activity cannot be halted, the following recommendations may reduce the effect of noise on the accuracy:

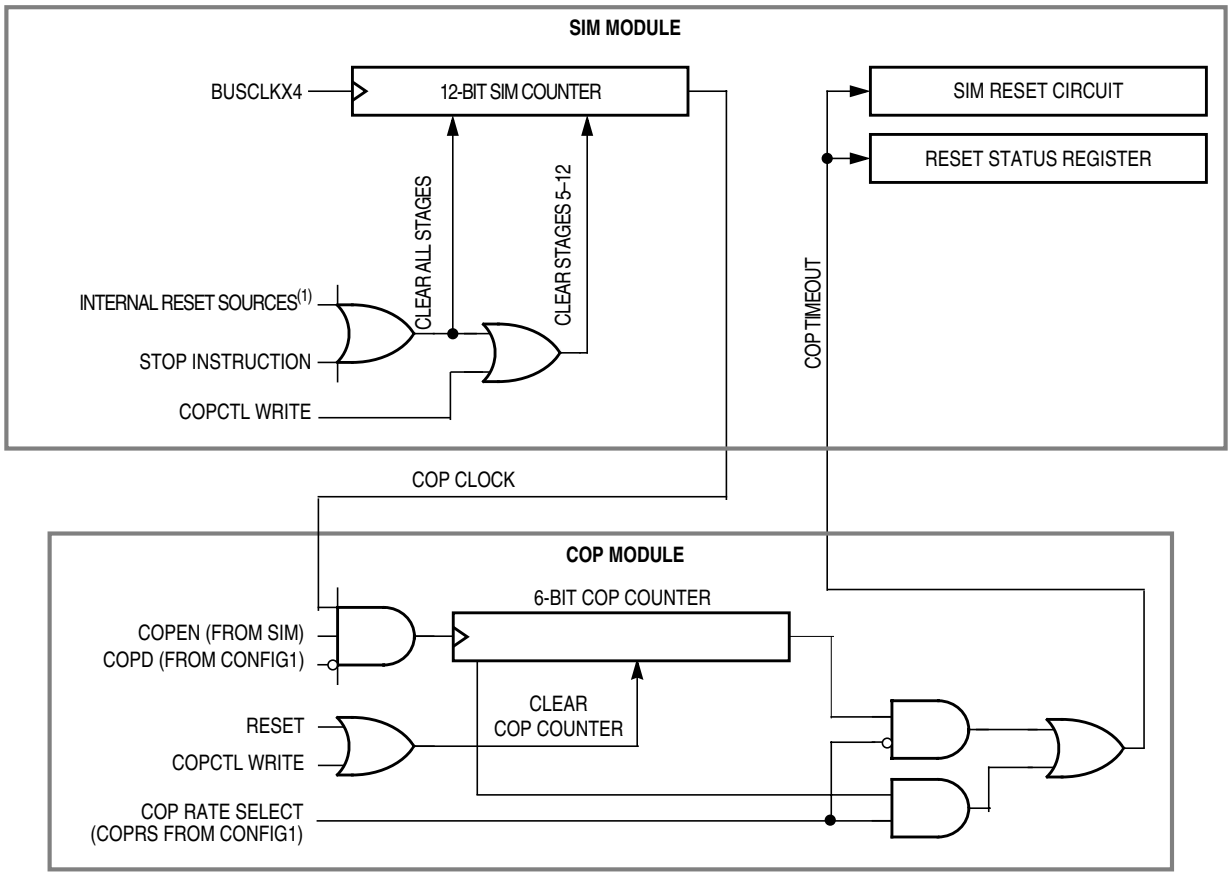
- Place a 0.01 µF capacitor on the selected input channel to V_{REFL} or V_{SSA} (if available). This will improve noise issues but will affect sample rate based on the external analog source resistance.
- Operate the ADC10 in stop mode by setting ACLKEN, selecting the channel in ADSCR, and executing a STOP instruction. This will reduce V_{DD} noise but will increase effective conversion time due to stop recovery.
- Average the input by converting the output many times in succession and dividing the sum of the results. Four samples are required to eliminate the effect of a 1LSB, one-time error.
- Reduce the effect of synchronous noise by operating off the asynchronous clock (ACLKEN=1) and averaging. Noise that is synchronous to the ADCK cannot be averaged out.

Chapter 5
Computer Operating Properly (COP)

5.1 Introduction

The computer operating properly (COP) module contains a free-running counter that generates a reset if allowed to overflow. The COP module helps software recover from runaway code. Prevent a COP reset by clearing the COP counter periodically. The COP module can be disabled through the COPD bit in the configuration 1 (CONFIG1) register.

5.2 Functional Description



1. See Chapter 14 System Integration Module (SIM) for more details.

Figure 5-1. COP Block Diagram

6.3.3 Stack Pointer

The stack pointer is a 16-bit register that contains the address of the next location on the stack. During a reset, the stack pointer is preset to $00FF. The reset stack pointer (RSP) instruction sets the least significant byte to $FF and does not affect the most significant byte. The stack pointer decrements as data is pushed onto the stack and increments as data is pulled from the stack.

In the stack pointer 8-bit offset and 16-bit offset addressing modes, the stack pointer can function as an index register to access data on the stack. The CPU uses the contents of the stack pointer to determine the conditional address of the operand.

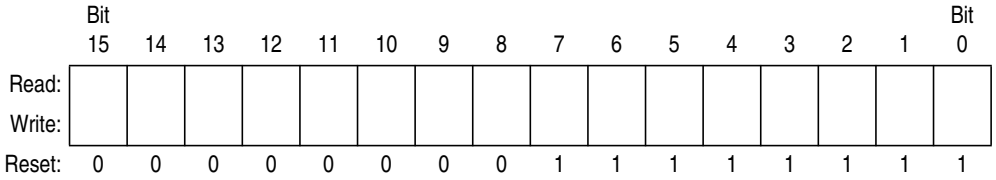


Figure 6-4. Stack Pointer (SP)

NOTE

The location of the stack is arbitrary and may be relocated anywhere in random-access memory (RAM). Moving the SP out of page 0 ($0000 to $00FF) frees direct address (page 0) space. For correct operation, the stack pointer must point only to RAM locations.

6.3.4 Program Counter

The program counter is a 16-bit register that contains the address of the next instruction or operand to be fetched.

Normally, the program counter automatically increments to the next sequential memory location every time an instruction or operand is fetched. Jump, branch, and interrupt operations load the program counter with an address other than that of the next sequential location.

During reset, the program counter is loaded with the reset vector address located at $FFFE and $FFFF. The vector address is the address of the first instruction to be executed after exiting the reset state.

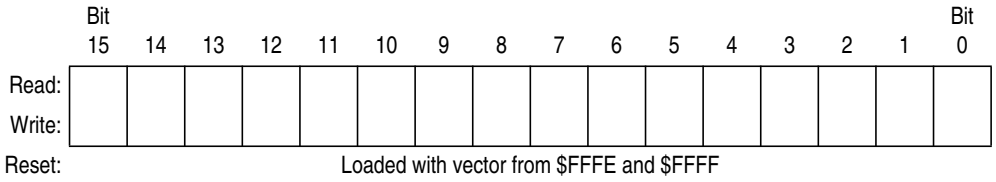


Figure 6-5. Program Counter (PC)

Table 6-1. Instruction Set Summary (Sheet 2 of 6)

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Cycles
			V	H	I	N	Z	C				
BHS *rel*	Branch if Higher or Same (Same as BCC)	PC ← (PC) + 2 + *rel* ? (C) = 0	–	–	–	–	–	–	REL	24	rr	3
BIH *rel*	Branch if $\overline{\text{IRQ}}$ Pin High	PC ← (PC) + 2 + *rel* ? $\overline{\text{IRQ}}$ = 1	–	–	–	–	–	–	REL	2F	rr	3
BIL *rel*	Branch if $\overline{\text{IRQ}}$ Pin Low	PC ← (PC) + 2 + *rel* ? $\overline{\text{IRQ}}$ = 0	–	–	–	–	–	–	REL	2E	rr	3
BIT #*opr* BIT *opr* BIT *opr* BIT *opr*,X BIT *opr*,X BIT ,X BIT *opr*,SP BIT *opr*,SP	Bit Test	(A) & (M)	0	–	–	↕	↕	–	IMM DIR EXT IX2 IX1 IX SP1 SP2	A5 B5 C5 D5 E5 F5 9EE5 9ED5	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5
BLE *opr*	Branch if Less Than or Equal To (Signed Operands)	PC ← (PC) + 2 + *rel* ? (Z) ∣ (N ⊕ V) = 1	–	–	–	–	–	–	REL	93	rr	3
BLO *rel*	Branch if Lower (Same as BCS)	PC ← (PC) + 2 + *rel* ? (C) = 1	–	–	–	–	–	–	REL	25	rr	3
BLS *rel*	Branch if Lower or Same	PC ← (PC) + 2 + *rel* ? (C) ∣ (Z) = 1	–	–	–	–	–	–	REL	23	rr	3
BLT *opr*	Branch if Less Than (Signed Operands)	PC ← (PC) + 2 + *rel* ? (N ⊕ V) =1	–	–	–	–	–	–	REL	91	rr	3
BMC *rel*	Branch if Interrupt Mask Clear	PC ← (PC) + 2 + *rel* ? (I) = 0	–	–	–	–	–	–	REL	2C	rr	3
BMI *rel*	Branch if Minus	PC ← (PC) + 2 + *rel* ? (N) = 1	–	–	–	–	–	–	REL	2B	rr	3
BMS *rel*	Branch if Interrupt Mask Set	PC ← (PC) + 2 + *rel* ? (I) = 1	–	–	–	–	–	–	REL	2D	rr	3
BNE *rel*	Branch if Not Equal	PC ← (PC) + 2 + *rel* ? (Z) = 0	–	–	–	–	–	–	REL	26	rr	3
BPL *rel*	Branch if Plus	PC ← (PC) + 2 + *rel* ? (N) = 0	–	–	–	–	–	–	REL	2A	rr	3
BRA *rel*	Branch Always	PC ← (PC) + 2 + *rel*	–	–	–	–	–	–	REL	20	rr	3
BRCLR *n*,*opr*,*rel*	Branch if Bit *n* in M Clear	PC ← (PC) + 3 + *rel* ? (Mn) = 0	–	–	–	–	–	↕	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	01 03 05 07 09 0B 0D 0F	dd rr dd rr dd rr dd rr dd rr dd rr dd rr dd rr	5 5 5 5 5 5 5 5
BRN *rel*	Branch Never	PC ← (PC) + 2	–	–	–	–	–	–	REL	21	rr	3
BRSET *n*,*opr*,*rel*	Branch if Bit *n* in M Set	PC ← (PC) + 3 + *rel* ? (Mn) = 1	–	–	–	–	–	↕	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	00 02 04 06 08 0A 0C 0E	dd rr dd rr dd rr dd rr dd rr dd rr dd rr dd rr	5 5 5 5 5 5 5 5
BSET *n*,*opr*	Set Bit *n* in M	Mn ← 1	–	–	–	–	–	–	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	10 12 14 16 18 1A 1C 1E	dd dd dd dd dd dd dd dd	4 4 4 4 4 4 4 4
BSR *rel*	Branch to Subroutine	PC ← (PC) + 2; push (PCL) SP ← (SP) – 1; push (PCH) SP ← (SP) – 1 PC ← (PC) + *rel*	–	–	–	–	–	–	REL	AD	rr	4
CBEQ *opr*,*rel* CBEQA #*opr*,*rel* CBEQX #*opr*,*rel* CBEQ *opr*,X+,*rel* CBEQ X+,*rel* CBEQ *opr*,SP,*rel*	Compare and Branch if Equal	PC ← (PC) + 3 + rel ? (A) – (M) = $00 PC ← (PC) + 3 + rel ? (A) – (M) = $00 PC ← (PC) + 3 + rel ? (X) – (M) = $00 PC ← (PC) + 3 + rel ? (A) – (M) = $00 PC ← (PC) + 2 + rel ? (A) – (M) = $00 PC ← (PC) + 4 + rel ? (A) – (M) = $00	–	–	–	–	–	–	DIR IMM IMM IX1+ IX+ SP1	31 41 51 61 71 9E61	dd rr ii rr ii rr ff rr rr ff rr	5 4 4 5 4 6
CLC	Clear Carry Bit	C ← 0	–	–	–	–	–	0	INH	98		1
CLI	Clear Interrupt Mask	I ← 0	–	–	0	–	–	–	INH	9A		2

When set, the IMASK bit in INTSCR masks the $\overline{IRQ}$ interrupt request. A latched interrupt request is not presented to the interrupt priority logic unless IMASK is clear.

NOTE

The interrupt mask (I) in the condition code register (CCR) masks all interrupt requests, including the $\overline{IRQ}$ interrupt request.

A falling edge on the $\overline{IRQ}$ pin can latch an interrupt request into the IRQ latch. An IRQ vector fetch, software clear, or reset clears the IRQ latch.

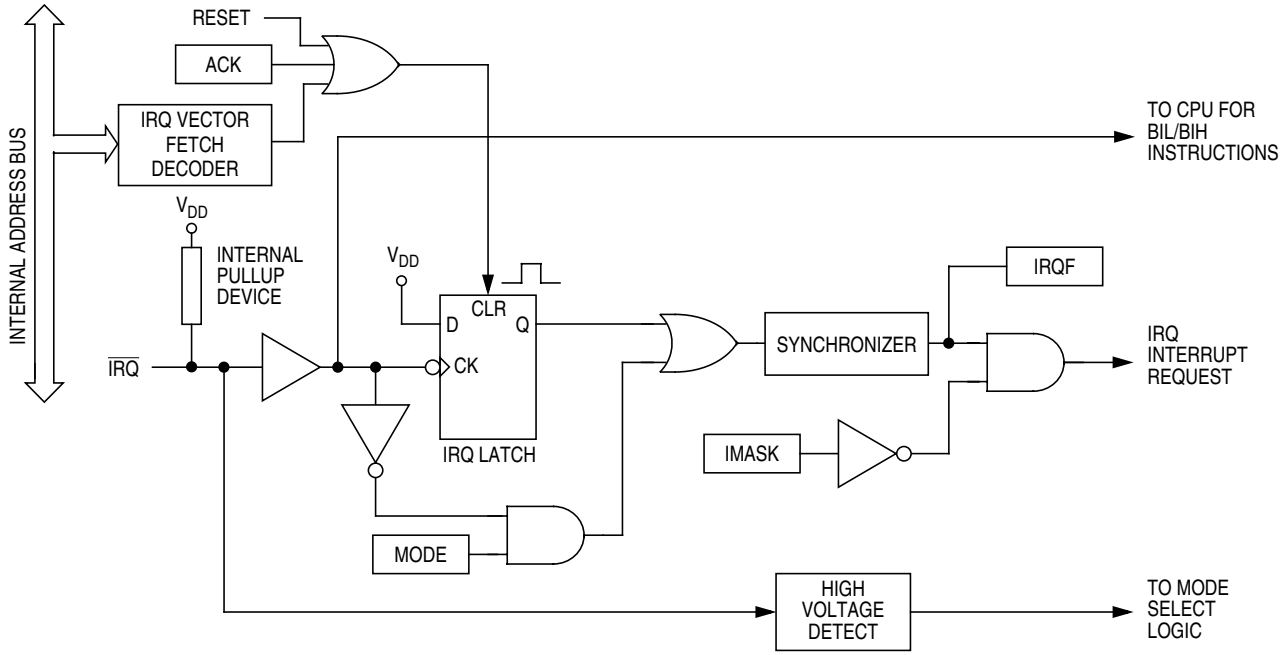


Figure 7-2. IRQ Module Block Diagram

7.3.1 MODE = 1

If the MODE bit is set, the $\overline{IRQ}$ pin is both falling edge sensitive and low level sensitive. With MODE set, both of the following actions must occur to clear the $\overline{IRQ}$ interrupt request:

- Return of the $\overline{IRQ}$ pin to a high level. As long as the $\overline{IRQ}$ pin is low, the IRQ request remains active.
- IRQ vector fetch or software clear. An IRQ vector fetch generates an interrupt acknowledge signal to clear the IRQ latch. Software generates the interrupt acknowledge signal by writing a 1 to ACK in INTSCR. The ACK bit is useful in applications that poll the $\overline{IRQ}$ pin and require software to clear the IRQ latch. Writing to ACK prior to leaving an interrupt service routine can also prevent spurious interrupts due to noise. Setting ACK does not affect subsequent transitions on the $\overline{IRQ}$ pin. A falling edge that occurs after writing to ACK latches another interrupt request. If the IRQ mask bit, IMASK, is clear, the CPU loads the program counter with the IRQ vector address.

The IRQ vector fetch or software clear and the return of the $\overline{IRQ}$ pin to a high level may occur in any order. The interrupt request remains pending as long as the $\overline{IRQ}$ pin is low. A reset will clear the IRQ latch and the MODE control bit, thereby clearing the interrupt even if the pin stays low.

Use the BIH or BIL instruction to read the logic level on the $\overline{IRQ}$ pin.

from $FFC0 into OSCTRIM if needed. The factory trim value provides the accuracy required for communication using force monitor mode. Trimming the device in the user application board will provide the most accurate trim value. See Oscillator Characteristics in the Electrical Chapter of this data book for additional information on factory trim.

10.3.2.2 Internal to External Clock Switching

When external clock source (external OSC, RC, or XTAL) is desired, the user must perform the following steps:

1. For external crystal circuits only, configure OSCOPT[1:0] to external crystal. To help precharge an external crystal oscillator, momentarily configure OSC2 as an output and drive it high for several cycles. This can help the crystal circuit start more robustly.
2. Configure OSCOPT[1:0] and ECFS[1:0] according to 10.8.1 Oscillator Status and Control Register. The oscillator module control logic will then enable OSC1 as an external clock input and, if the external crystal option is selected, OSC2 will also be enabled as the clock output. If RC oscillator option is selected, enabling the OSC2 output may change the bus frequency.
3. Create a software delay to provide the stabilization time required for the selected clock source (crystal, resonator, RC). A good rule of thumb for crystal oscillators is to wait 4096 cycles of the crystal frequency; i.e., for a 4-MHz crystal, wait approximately 1 ms.
4. After the stabilization delay has elapsed, set ECGON.

After ECGON set is detected, the OSC module checks for oscillator activity by waiting two external clock rising edges. The OSC module then switches to the external clock. Logic provides a coherent transition. The OSC module first sets ECGST and then stops the internal oscillator.

10.3.2.3 External to Internal Clock Switching

After following the procedures to switch to an external clock source, it is possible to go back to the internal source. By clearing the OSCOPT[1:0] bits and clearing the ECGON bit, the external circuit will be disengaged. The bus clock will be derived from the selected internal clock source based on the ICFS[1:0] bits.

10.3.3 External Oscillator

The external oscillator option is designed for use when a clock signal is available in the application to provide a clock source to the MCU. The OSC1 pin is enabled as an input by the oscillator module. The clock signal is used directly to create BUSCLKX4 and also divided by two to create BUSCLKX2.

In this configuration, the OSC2 pin cannot output BUSCLKX4. The OSC2EN bit will be forced clear to enable alternative functions on the pin.

10.3.4 XTAL Oscillator

The XTAL oscillator circuit is designed for use with an external crystal or ceramic resonator to provide an accurate clock source. In this configuration, the OSC2 pin is dedicated to the external crystal circuit. The OSC2EN bit has no effect when this clock mode is selected.

In its typical configuration, the XTAL oscillator is connected in a Pierce oscillator configuration, as shown in Figure 10-2. This figure shows only the logical representation of the internal components and may not represent actual circuitry.

13.8.3 ESCI Control Register 3

ESCI control register 3 (SCC3):

- Stores the ninth ESCI data bit received and the ninth ESCI data bit to be transmitted.
- Enables these interrupts:
  - Receiver overrun
  - Noise error
  - Framing error
  - Parity error

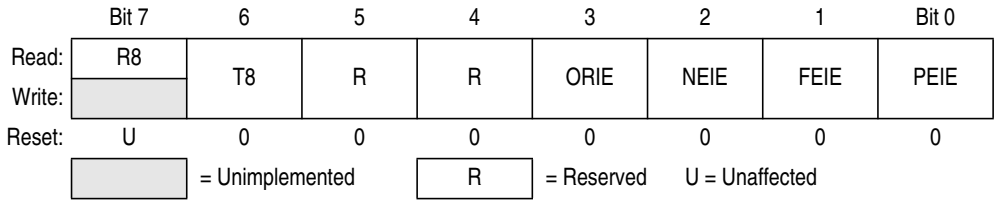


Figure 13-11. ESCI Control Register 3 (SCC3)

R8 — Received Bit 8

When the ESCI is receiving 9-bit characters, R8 is the read-only ninth bit (bit 8) of the received character. R8 is received at the same time that the SCDR receives the other 8 bits.

When the ESCI is receiving 8-bit characters, R8 is a copy of the eighth bit (bit 7).

T8 — Transmitted Bit 8

When the ESCI is transmitting 9-bit characters, T8 is the read/write ninth bit (bit 8) of the transmitted character. T8 is loaded into the transmit shift register at the same time that the SCDR is loaded into the transmit shift register.

ORIE — Receiver Overrun Interrupt Enable Bit

This read/write bit enables ESCI error interrupt requests generated by the receiver overrun bit, OR.

1 = ESCI error interrupt requests from OR bit enabled
0 = ESCI error interrupt requests from OR bit disabled

NEIE — Receiver Noise Error Interrupt Enable Bit

This read/write bit enables ESCI error interrupt requests generated by the noise error bit, NE.

1 = ESCI error interrupt requests from NE bit enabled
0 = ESCI error interrupt requests from NE bit disabled

FEIE — Receiver Framing Error Interrupt Enable Bit

This read/write bit enables ESCI error interrupt requests generated by the framing error bit, FE.

1 = ESCI error interrupt requests from FE bit enabled
0 = ESCI error interrupt requests from FE bit disabled

PEIE — Receiver Parity Error Interrupt Enable Bit

This read/write bit enables ESCI receiver interrupt requests generated by the parity error bit, PE.

1 = ESCI error interrupt requests from PE bit enabled
0 = ESCI error interrupt requests from PE bit disabled

14.3.1 Bus Timing

In user mode, the internal bus frequency is the oscillator frequency (BUSCLKX4) divided by four.

14.3.2 Clock Start-Up from POR

When the power-on reset module generates a reset, the clocks to the CPU and peripherals are inactive and held in an inactive phase until after the 4096 BUSCLKX4 cycle POR time out has completed. The IBUS clocks start upon completion of the time out.

14.3.3 Clocks in Stop Mode and Wait Mode

Upon exit from stop mode by an interrupt or reset, the SIM allows BUSCLKX4 to clock the SIM counter. The CPU and peripheral clocks do not become active until after the stop delay time out. This time out is selectable as 4096 or 32 BUSCLKX4 cycles. See 14.7.2 Stop Mode.

In wait mode, the CPU clocks are inactive. The SIM also produces two sets of clocks for other modules. Refer to the wait mode subsection of each module to see if the module is active or inactive in wait mode. Some modules can be programmed to be active in wait mode.

14.4 Reset and System Initialization

The MCU has these reset sources:

- Power-on reset module (POR)
- External reset pin ($\overline{RST}$)
- Computer operating properly module (COP)
- Low-voltage inhibit module (LVI)
- Illegal opcode
- Illegal address

All of these resets produce the vector $FFFE–FFFF ($FEFE–FEFF in monitor mode) and assert the internal reset signal (IRST). IRST causes all registers to be returned to their default values and all modules to be returned to their reset states.

An internal reset clears the SIM counter (see 14.5 SIM Counter), but an external reset does not. Each of the resets sets a corresponding bit in the SIM reset status register (SRSR). See 14.8 SIM Registers.

14.4.1 External Pin Reset

The $\overline{RST}$ pin circuits include an internal pullup device. Pulling the asynchronous $\overline{RST}$ pin low halts all processing. The PIN bit of the SIM reset status register (SRSR) is set as long as $\overline{RST}$ is held low for at least the minimum t_{RL} time. Figure 14-3 shows the relative timing. The $\overline{RST}$ pin function is only available if the RSTEN bit is set in the CONFIG2 register.

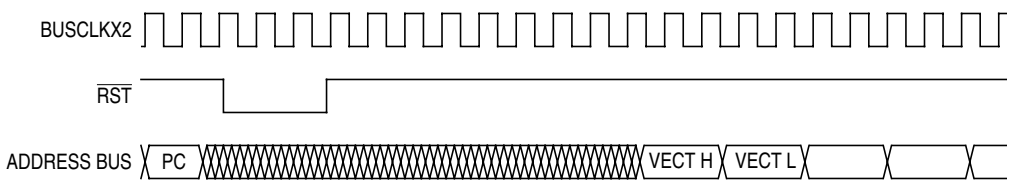
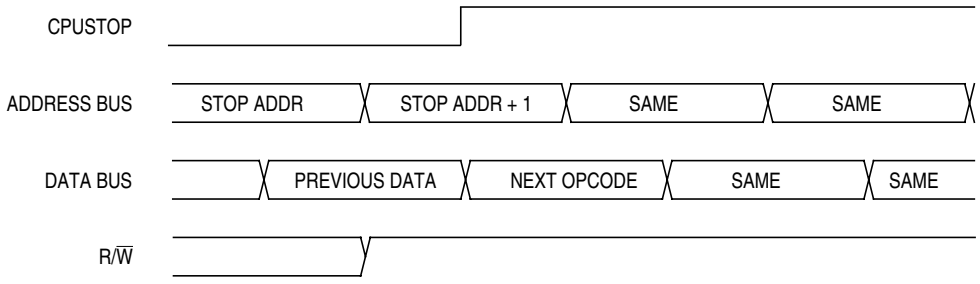


Figure 14-3. External Reset Timing

The SIM counter is held in reset from the execution of the STOP instruction until the beginning of stop recovery. It is then used to time the recovery period. Figure 14-17 shows stop mode entry timing and Figure 14-18 shows the stop mode recovery time from interrupt or break

NOTE

To minimize stop current, all pins configured as inputs should be driven to a logic 1 or logic 0.



NOTE: Previous data can be operand data or the STOP opcode, depending on the last instruction.

Figure 14-17. Stop Mode Entry Timing

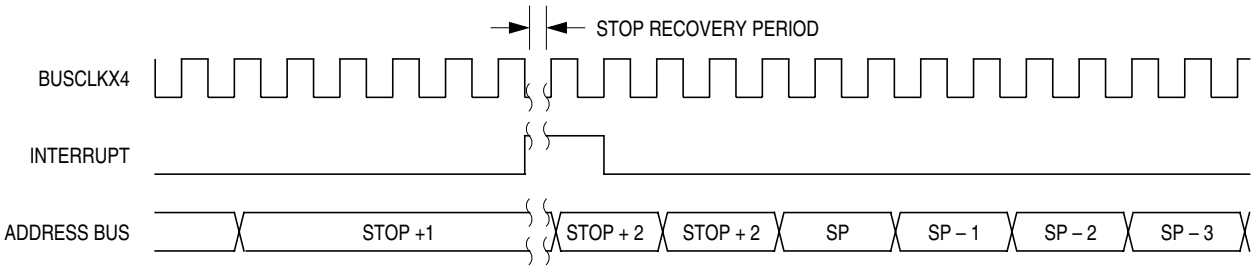


Figure 14-18. Stop Mode Recovery from Interrupt

14.8 SIM Registers

The SIM has three memory mapped registers. Table 14-4 shows the mapping of these registers.

Table 14-4. SIM Registers

Address	Register	Access Mode
$FE00	BSR	User
$FE01	SRSR	User
$FE03	BFCR	User

input ($\overline{SS}$) is low, so that only the selected slave drives to the master. The $\overline{SS}$ pin of the master is not shown but is assumed to be inactive. The $\overline{SS}$ pin of the master must be high or must be reconfigured as general-purpose I/O not affecting the SPI. (See 15.3.6.2 Mode Fault Error.) When CPHA = 0, the first SPSCK edge is the MSB capture strobe. Therefore, the slave must begin driving its data before the first SPSCK edge, and a falling edge on the $\overline{SS}$ pin is used to start the slave data transmission. The slave's $\overline{SS}$ pin must be toggled back to high and then low again between each byte transmitted as shown in Figure 15-5.

When CPHA = 0 for a slave, the falling edge of $\overline{SS}$ indicates the beginning of the transmission. This causes the SPI to leave its idle state and begin driving the MISO pin with the MSB of its data. After the transmission begins, no new data is allowed into the shift register from the transmit data register. Therefore, the SPI data register of the slave must be loaded with transmit data before the falling edge of $\overline{SS}$. Any data written after the falling edge is stored in the transmit data register and transferred to the shift register after the current transmission.

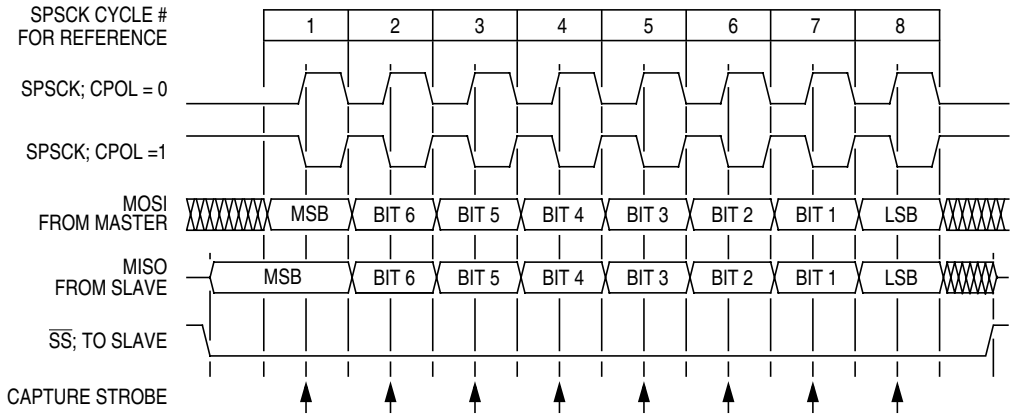


Figure 15-4. Transmission Format (CPHA = 0)

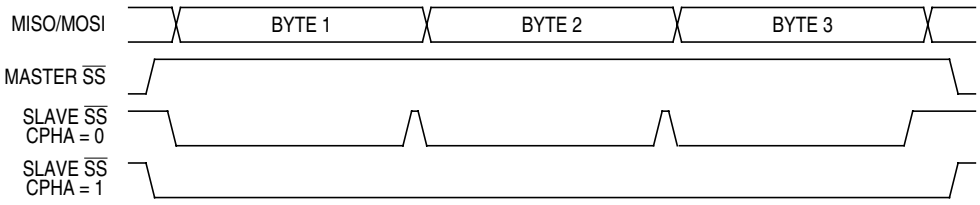


Figure 15-5. CPHA/$\overline{SS}$ Timing

15.3.3.3 Transmission Format When CPHA = 1

Figure 15-6 shows an SPI transmission in which CPHA = 1. The figure should not be used as a replacement for data sheet parametric information. Two waveforms are shown for SPSCK: one for CPOL = 0 and another for CPOL = 1. The diagram may be interpreted as a master or slave timing diagram because the serial clock (SPSCK), master in/slave out (MISO), and master out/slave in (MOSI) pins are directly connected between the master and the slave. The MISO signal is the output from the slave, and the MOSI signal is the output from the master. The $\overline{SS}$ line is the slave select input to the slave. The slave SPI drives its MISO output only when its slave select input ($\overline{SS}$) is low, so that only the selected slave drives to the master. The $\overline{SS}$ pin of the master is not shown but is assumed to be inactive. The $\overline{SS}$

the second transmission example, the OVRF bit can be set in between the time that SPSCR and SPDR are read.

In this case, an overflow can be missed easily. Because no more SPRF interrupts can be generated until this OVRF is serviced, it is not obvious that bytes are being lost as more transmissions are completed. To prevent this, either enable the OVRF interrupt or do another read of the SPSCR following the read of the SPDR. This ensures that the OVRF was not set before the SPRF was cleared and that future transmissions can set the SPRF bit. Figure 15-10 illustrates this process. Generally, to avoid this second SPSCR read, enable OVRF by setting the ERRIE bit.

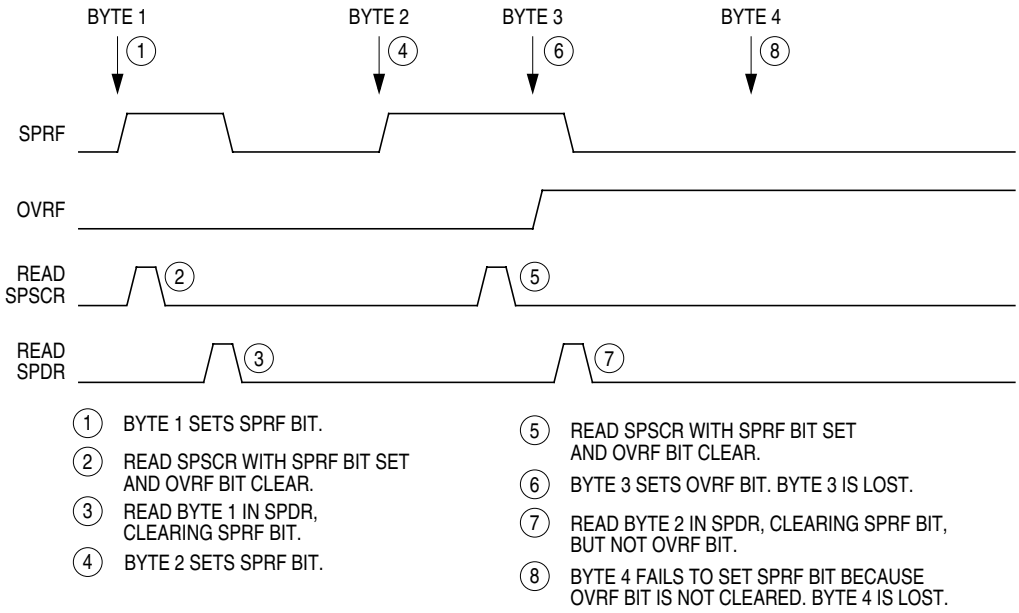


Figure 15-9. Missed Read of Overflow Condition

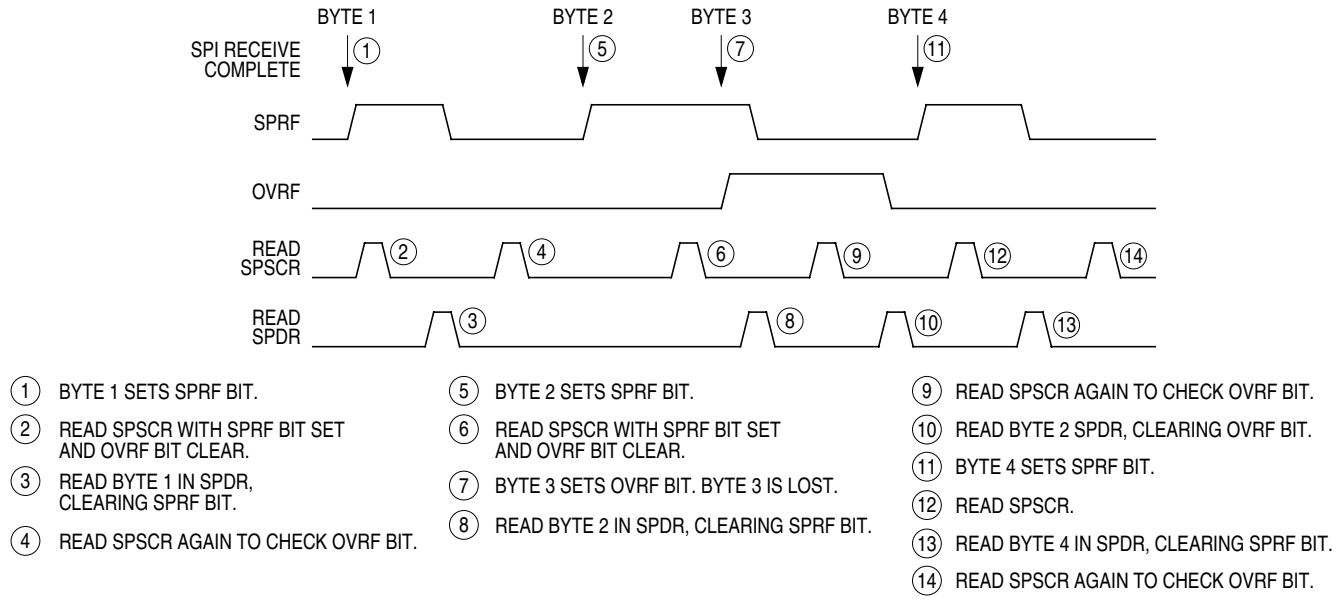


Figure 15-10. Clearing SPRF When OVRF Interrupt Is Not Enabled

16.8.5 TIM1 Channel Registers

These read/write registers contain the captured counter value of the input capture function or the output compare value of the output compare function. The state of the TIM1 channel registers after reset is unknown.

In input capture mode (MSxB:MSxA = 0:0), reading the high byte of the TIM1 channel x registers (T1CHxH) inhibits input captures until the low byte (T1CHxL) is read.

In output compare mode (MSxB:MSxA ≠ 0:0), writing to the high byte of the TIM1 channel x registers (T1CHxH) inhibits output compares until the low byte (T1CHxL) is written.

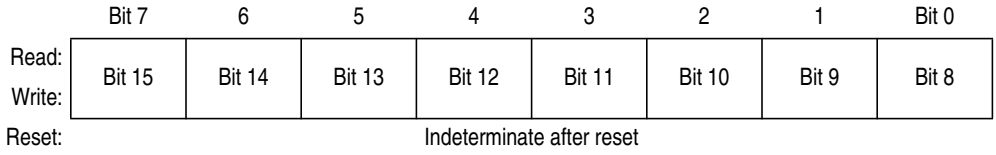


Figure 16-14. TIM1 Channel x Register High (T1CHxH)

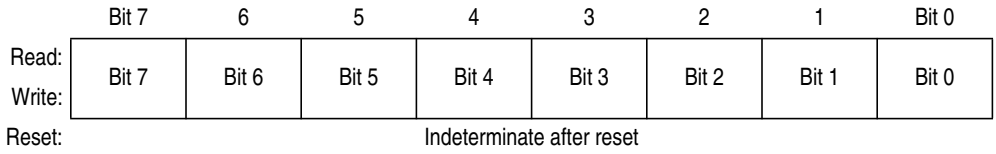


Figure 16-15. TIM1 Channel Register Low (T1CHxL)

Table 18-7. READSP (Read Stack Pointer) Command

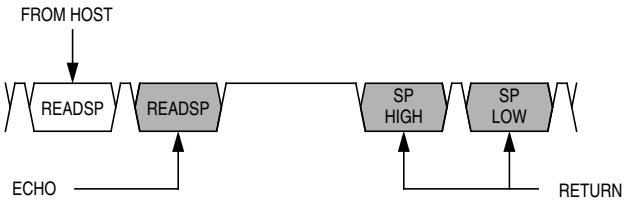
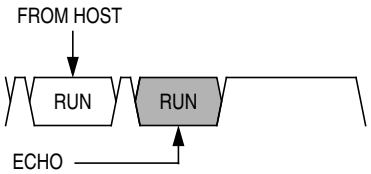
Description	Reads stack pointer
Operand	None
Data Returned	Returns incremented stack pointer value (SP + 1) in high-byte:low-byte order
Opcode	$0C
Command Sequence	

Table 18-8. RUN (Run User Program) Command

Description	Executes PULH and RTI instructions
Operand	None
Data Returned	None
Opcode	$28
Command Sequence	

The MCU executes the SWI and PSHH instructions when it enters monitor mode. The RUN command tells the MCU to execute the PULH and RTI instructions. Before sending the RUN command, the host can modify the stacked CPU registers to prepare to run the host program. The READSP command returns the incremented stack pointer value, SP + 1. The high and low bytes of the program counter are at addresses SP + 5 and SP + 6.

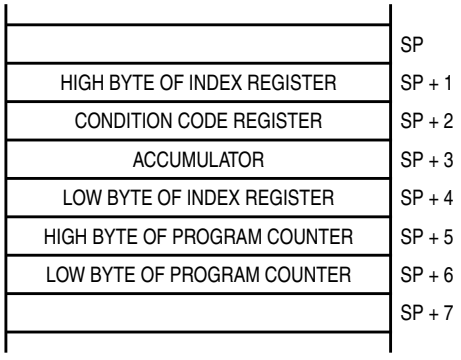


Figure 18-17. Stack Pointer at Monitor Mode Entry

NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M–1994.

2. DIMENSIONS IN MILLIMETERS.

3. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.15 PER END.

4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR MOLD PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.

5. DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSIONS. DAM BAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.38.

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE:	DOCUMENT NO: 98ARS23923W	REV: C
28 LEAD 0.65 PITCH TSSOP 4.4 WIDE BODY, 1.2 MAX HEIGHT	CASE NUMBER: 1168-02	18 AUG 2006
	STANDARD: JEDEC MO-153 AE	

NOTES:

1. CONTROLLING DIMENSION: MILLIMETER

2. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M-1982.

3. DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.

5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE DIMENSION AT MAXIMUM MATERIAL CONDITION.

6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

7. DIMENSIONS ARE TO BE DETERMINED AT DATUM PLANE -W-.

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE:	DOCUMENT NO: 98ASH70247A	REV: B
16 LD TSSOP, PITCH 0.65MM	CASE NUMBER: 948F-01	19 MAY 2005
	STANDARD: JEDEC	